

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.16	100.0	2.25
	Pure metal	Aluminium (Al)	7429-90-5	0.01	100.0	0.15
Subtotal				0.17	200	2.4
Die	Doped silicon	Silicon (Si)	7440-21-3	0.3	100.0	4.4
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.72	100.0	25
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02	0.04	0.34
	Copper alloy	Iron (Fe)	7439-89-6	0.06	0.1	0.84
	Copper alloy	Copper (Cu)	7440-50-8	57.81	99.86	838.82
Subtotal				57.89	100	840
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	3.37	8.7	48.94
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6.2	16.0	90
	Filler	Silica fused	60676-86-0	29.08	75.0	421.88
	Carbon Black	Carbon black	1333-86-4	0.12	0.3	1.69
	Subtotal				38.77	100
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.06	5.0	0.83
	Lead alloy	Silver (Ag)	7440-22-4	0.03	2.5	0.42
	Lead alloy	Lead (Pb)	7439-92-1	1.06	92.5	15.42
Subtotal				1.15	100	16.67
Total				100	100	1450.98

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